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Understanding <u>Embedded - CPLDs (Complex</u> <u>Programmable Logic Devices)</u>

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixedfunction ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

2000	
Product Status	Obsolete
Programmable Type	EE PLD
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	4
Number of Macrocells	64
Number of Gates	1250
Number of I/O	36
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7064lc44-10

Email: info@E-XFL.COM

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	 Additional design entry and simulation support provided by EDIF 2 0 0 and 3 0 0 netlist files, library of parameterized modules (LPM), Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, and VeriBest Programming support Altera's Master Programming Unit (MPU) and programming hardware from third-party manufacturers program all MAX 7000 devices The BitBlasterTM serial download cable, ByteBlasterMVTM parallel port download cable, and MasterBlasterTM serial/universal serial bus (USB) download cable program MAX 7000S devices
General Description	The MAX 7000 family of high-density, high-performance PLDs is based on Altera's second-generation MAX architecture. Fabricated with advanced CMOS technology, the EEPROM-based MAX 7000 family provides 600 to 5,000 usable gates, ISP, pin-to-pin delays as fast as 5 ns, and counter speeds of up to 175.4 MHz. MAX 7000S devices in the -5, -6, -7, and -10 speed grades as well as MAX 7000 and MAX 7000E devices in -5, -6, -7, -10P, and -12P speed grades comply with the PCI Special Interest Group (PCI SIG) <i>PCI Local Bus Specification, Revision 2.2.</i> See Table 3 for available speed grades.

Device	Speed Grade										
	-5	-6	-7	-10P	-10	-12P	-12	-15	-15T	-20	
EPM7032		>	~		>		>	~	 		
EPM7032S	\checkmark	\checkmark	~		 Image: A start of the start of						
EPM7064		>	~		>		>	~			
EPM7064S	\checkmark	\checkmark	~		 Image: A start of the start of						
EPM7096			\checkmark		\checkmark		>	\checkmark			
EPM7128E			~	\checkmark	 Image: A start of the start of		>	~		~	
EPM7128S		\checkmark	~		 Image: A start of the start of			~			
EPM7160E				~	~		\checkmark	~		\checkmark	
EPM7160S		\checkmark	~		 Image: A start of the start of			~			
EPM7192E						~	>	~		>	
EPM7192S			~	1	~	Ī		~			
EPM7256E						~	>	~		>	
EPM7256S			\checkmark		\checkmark			\checkmark			

The MAX 7000E devices—including the EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices—have several enhanced features: additional global clocking, additional output enable controls, enhanced interconnect resources, fast input registers, and a programmable slew rate.

In-system programmable MAX 7000 devices—called MAX 7000S devices—include the EPM7032S, EPM7064S, EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices. MAX 7000S devices have the enhanced features of MAX 7000E devices as well as JTAG BST circuitry in devices with 128 or more macrocells, ISP, and an open-drain output option. See Table 4.

Feature	EPM7032 EPM7064 EPM7096	All MAX 7000E Devices	All MAX 7000S Devices
ISP via JTAG interface			\checkmark
JTAG BST circuitry			✓(1)
Open-drain output option			\checkmark
Fast input registers		~	\checkmark
Six global output enables		~	\checkmark
Two global clocks		~	\checkmark
Slew-rate control		~	\checkmark
MultiVolt interface (2)	\checkmark	~	\checkmark
Programmable register	\checkmark	~	\checkmark
Parallel expanders	\checkmark	~	\checkmark
Shared expanders	\checkmark	~	\checkmark
Power-saving mode	\checkmark	~	\checkmark
Security bit	\checkmark	~	\checkmark
PCI-compliant devices available	\checkmark	\checkmark	\checkmark

Notes:

(1) Available only in EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices only.

(2) The MultiVolt I/O interface is not available in 44-pin packages.

The MAX 7000 architecture includes four dedicated inputs that can be used as general-purpose inputs or as high-speed, global control signals (clock, clear, and two output enable signals) for each macrocell and I/O pin. Figure 1 shows the architecture of EPM7032, EPM7064, and EPM7096 devices.

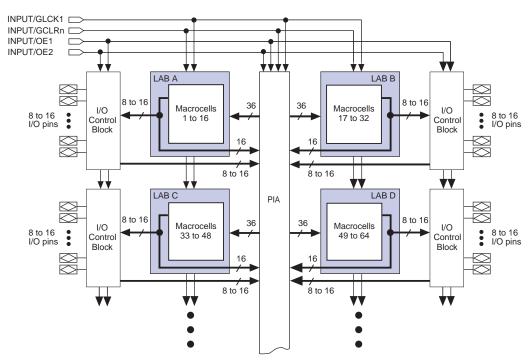
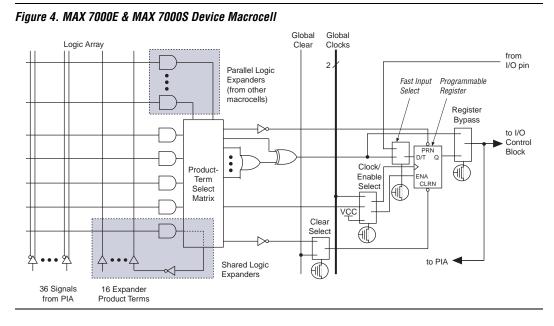
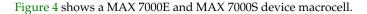


Figure 1. EPM7032, EPM7064 & EPM7096 Device Block Diagram





Combinatorial logic is implemented in the logic array, which provides five product terms per macrocell. The product-term select matrix allocates these product terms for use as either primary logic inputs (to the OR and XOR gates) to implement combinatorial functions, or as secondary inputs to the macrocell's register clear, preset, clock, and clock enable control functions. Two kinds of expander product terms ("expanders") are available to supplement macrocell logic resources:

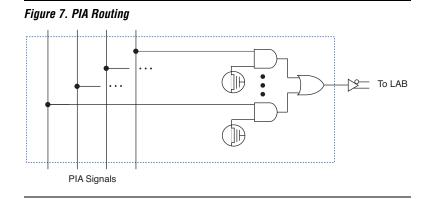
- Shareable expanders, which are inverted product terms that are fed back into the logic array
- Parallel expanders, which are product terms borrowed from adjacent macrocells

The Altera development system automatically optimizes product-term allocation according to the logic requirements of the design.

For registered functions, each macrocell flipflop can be individually programmed to implement D, T, JK, or SR operation with programmable clock control. The flipflop can be bypassed for combinatorial operation. During design entry, the designer specifies the desired flipflop type; the Altera development software then selects the most efficient flipflop operation for each registered function to optimize resource utilization.

Programmable Interconnect Array

Logic is routed between LABs via the programmable interconnect array (PIA). This global bus is a programmable path that connects any signal source to any destination on the device. All MAX 7000 dedicated inputs, I/O pins, and macrocell outputs feed the PIA, which makes the signals available throughout the entire device. Only the signals required by each LAB are actually routed from the PIA into the LAB. Figure 7 shows how the PIA signals are routed into the LAB. An EEPROM cell controls one input to a 2-input AND gate, which selects a PIA signal to drive into the LAB.



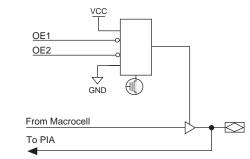
While the routing delays of channel-based routing schemes in masked or FPGAs are cumulative, variable, and path-dependent, the MAX 7000 PIA has a fixed delay. The PIA thus eliminates skew between signals and makes timing performance easy to predict.

I/O Control Blocks

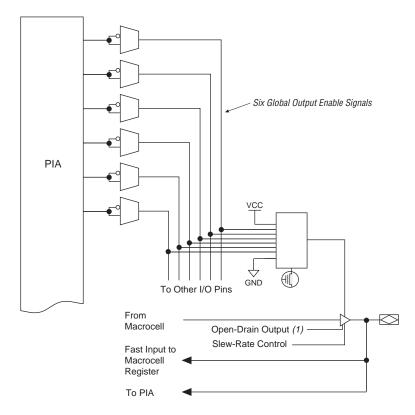
The I/O control block allows each I/O pin to be individually configured for input, output, or bidirectional operation. All I/O pins have a tri-state buffer that is individually controlled by one of the global output enable signals or directly connected to ground or V_{CC} . Figure 8 shows the I/O control block for the MAX 7000 family. The I/O control block of EPM7032, EPM7064, and EPM7096 devices has two global output enable signals that are driven by two dedicated active-low output enable pins (OE1 and OE2). The I/O control block of MAX 7000E and MAX 7000S devices has six global output enable signals that are driven by the true or complement of two output enable signals, a subset of the I/O pins, or a subset of the I/O macrocells.

Figure 8. I/O Control Block of MAX 7000 Devices

EPM7032, EPM7064 & EPM7096 Devices







Note:

(1) The open-drain output option is available only in MAX 7000S devices.

Table 15. MAX 7000 5.0-V Device DC Operating Conditions Note (9)										
Symbol	Parameter	Conditions	Min	Max	Unit					
V _{IH}	High-level input voltage		2.0	V _{CCINT} + 0.5	V					
V _{IL}	Low-level input voltage		-0.5 (8)	0.8	V					
V _{OH}	5.0-V high-level TTL output voltage	$I_{OH} = -4 \text{ mA DC}, V_{CCIO} = 4.75 \text{ V} (10)$	2.4		V					
	3.3-V high-level TTL output voltage	$I_{OH} = -4 \text{ mA DC}, V_{CCIO} = 3.00 \text{ V} (10)$	2.4		V					
,	3.3-V high-level CMOS output voltage	I_{OH} = -0.1 mA DC, V_{CCIO} = 3.0 V (10)	V _{CCIO} – 0.2		V					
V _{OL}	5.0-V low-level TTL output voltage	I _{OL} = 12 mA DC, V _{CCIO} = 4.75 V (11)		0.45	V					
	3.3-V low-level TTL output voltage	I _{OL} = 12 mA DC, V _{CCIO} = 3.00 V (11)		0.45	V					
	3.3-V low-level CMOS output voltage	I _{OL} = 0.1 mA DC, V _{CCIO} = 3.0 V(11)		0.2	V					
I _I	Leakage current of dedicated input pins	$V_{I} = -0.5$ to 5.5 V (11)	-10	10	μΑ					
I _{OZ}	I/O pin tri-state output off-state current	V _I = -0.5 to 5.5 V (11), (12)	-40	40	μA					

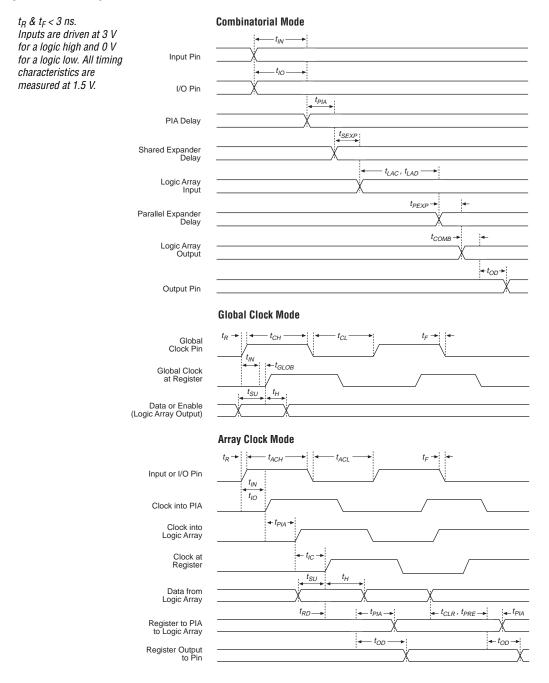
Table 1	Table 16. MAX 7000 5.0-V Device Capacitance: EPM7032, EPM7064 & EPM7096 Devices Note (13)								
Symbol	Parameter	Conditions	Min	Max	Unit				
CIN	Input pin capacitance	V _{IN} = 0 V, f = 1.0 MHz		12	pF				
C _{I/O}	I/O pin capacitance	V _{OUT} = 0 V, f = 1.0 MHz		12	pF				

Table 1	Table 17. MAX 7000 5.0-V Device Capacitance: MAX 7000E Devices Note (13)									
Symbol	Parameter	Conditions	Min	Max	Unit					
C _{IN}	Input pin capacitance	V _{IN} = 0 V, f = 1.0 MHz		15	pF					
C _{I/O}	I/O pin capacitance	V _{OUT} = 0 V, f = 1.0 MHz		15	pF					

Table 1	Table 18. MAX 7000 5.0-V Device Capacitance: MAX 7000S Devices Note (13)									
Symbol	Parameter	Conditions	Min	Max	Unit					
CIN	Dedicated input pin capacitance	V _{IN} = 0 V, f = 1.0 MHz		10	pF					
C _{I/O}	I/O pin capacitance	V _{OUT} = 0 V, f = 1.0 MHz		10	pF					

.

Figure 13. Switching Waveforms



Symbol	Parameter	Conditions		Speed	Grade		Unit
			MAX 700	0E (-10P)		00 (-10) Doe (-10)	
			Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.5		1.0	ns
t _{IO}	I/O input pad and buffer delay			0.5		1.0	ns
t _{FIN}	Fast input delay	(2)		1.0		1.0	ns
t _{SEXP}	Shared expander delay			5.0		5.0	ns
t _{PEXP}	Parallel expander delay			0.8		0.8	ns
t _{LAD}	Logic array delay			5.0		5.0	ns
t _{LAC}	Logic control array delay			5.0		5.0	ns
t _{IOE}	Internal output enable delay	(2)		2.0		2.0	ns
t _{OD1}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		1.5		2.0	ns
t _{OD2}	Output buffer and pad delay Slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF (7)		2.0		2.5	ns
t _{OD3}	Output buffer and pad delay Slow slew rate = on $V_{CCIO} = 5.0 V \text{ or } 3.3 V$	C1 = 35 pF (2)		5.5		6.0	ns
t _{ZX1}	Output buffer enable delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		5.0		5.0	ns
t _{ZX2}	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF (7)		5.5		5.5	ns
t _{ZX3}	Output buffer enable delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		9.0		9.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		5.0		5.0	ns
t _{SU}	Register setup time		2.0		3.0		ns
t _H	Register hold time		3.0		3.0		ns
t _{FSU}	Register setup time of fast input	(2)	3.0		3.0		ns
t _{FH}	Register hold time of fast input	(2)	0.5		0.5		ns
t _{RD}	Register delay			2.0		1.0	ns
t _{COMB}	Combinatorial delay			2.0		1.0	ns
t _{IC}	Array clock delay			5.0		5.0	ns
t _{EN}	Register enable time			5.0		5.0	ns
t _{GLOB}	Global control delay			1.0		1.0	ns
t _{PRE}	Register preset time			3.0		3.0	ns
t _{CLR}	Register clear time			3.0		3.0	ns
t _{PIA}	PIA delay			1.0		1.0	ns
t _{LPA}	Low-power adder	(8)		11.0		11.0	ns

Symbol	Parameter	Conditions			Speed	Grade			Unit
			-	15	-1	5T	-2	20	
			Min	Max	Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			2.0		2.0		3.0	ns
t _{IO}	I/O input pad and buffer delay			2.0		2.0		3.0	ns
t _{FIN}	Fast input delay	(2)		2.0		-		4.0	ns
t _{SEXP}	Shared expander delay			8.0		10.0		9.0	ns
t _{PEXP}	Parallel expander delay			1.0		1.0		2.0	ns
t _{LAD}	Logic array delay			6.0		6.0		8.0	ns
tLAC	Logic control array delay			6.0		6.0		8.0	ns
t _{IOE}	Internal output enable delay	(2)		3.0		-		4.0	ns
t _{OD1}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		4.0		4.0		5.0	ns
t _{OD2}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		5.0		-		6.0	ns
t _{OD3}	Output buffer and pad delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		8.0		-		9.0	ns
t _{ZX1}	Output buffer enable delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		6.0		6.0		10.0	ns
t _{ZX2}	Output buffer enable delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		7.0		-		11.0	ns
t _{ZX3}	Output buffer enable delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		10.0		-		14.0	ns
t _{XZ}	Output buffer disable delay	C1 = 5 pF		6.0		6.0		10.0	ns
t _{SU}	Register setup time		4.0		4.0		4.0		ns
t _H	Register hold time		4.0		4.0		5.0		ns
t _{FSU}	Register setup time of fast input	(2)	2.0		-		4.0		ns
t _{FH}	Register hold time of fast input	(2)	2.0		-		3.0		ns
t _{RD}	Register delay			1.0		1.0		1.0	ns
t _{COMB}	Combinatorial delay			1.0		1.0		1.0	ns
t _{IC}	Array clock delay			6.0		6.0		8.0	ns
t _{EN}	Register enable time			6.0		6.0		8.0	ns
t _{GLOB}	Global control delay			1.0		1.0		3.0	ns
t _{PRE}	Register preset time			4.0		4.0		4.0	ns
t _{CLR}	Register clear time			4.0		4.0		4.0	ns
t _{PIA}	PIA delay			2.0		2.0		3.0	ns
t _{LPA}	Low-power adder	(8)		13.0		15.0		15.0	ns

Notes to tables:

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This parameter applies to MAX 7000E devices only.
- (3) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (4) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (5) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (6) The f_{MAX} values represent the highest frequency for pipelined data.
- (7) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 27 and 28 show the EPM7032S AC operating conditions.

Symbol	Parameter	Conditions				Speed	Grade				Unit
			-	5	-	6	-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t _{SU}	Global clock setup time		2.9		4.0		5.0		7.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		2.5		2.5		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.0		0.5		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		3.2		3.5		4.3		5.0	ns
t _{CH}	Global clock high time		2.0		2.5		3.0		4.0		ns
t _{CL}	Global clock low time		2.0		2.5		3.0		4.0		ns
t _{ASU}	Array clock setup time		0.7		0.9		1.1		2.0		ns
t _{AH}	Array clock hold time		1.8		2.1		2.7		3.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		5.4		6.6		8.2		10.0	ns
t _{ACH}	Array clock high time		2.5		2.5		3.0		4.0		ns
t _{ACL}	Array clock low time		2.5		2.5		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			5.7		7.0		8.6		10.0	ns
f _{CNT}	Maximum internal global clock frequency	(4)	175.4		142.9		116.3		100.0		MHz
t _{ACNT}	Minimum array clock period			5.7		7.0		8.6		10.0	ns

Table 2	Table 27. EPM7032S External Timing Parameters (Part 2 of 2) Note (1)										
Symbol	Parameter	Conditions				Speed	Grade				Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
f _{ACNT}	Maximum internal array clock frequency	(4)	175.4		142.9		116.3		100.0		MHz
f _{MAX}	Maximum clock frequency	(5)	250.0		200.0		166.7		125.0		MHz

Symbol	Parameter	Conditions	Speed Grade									
			-5		-6		-7		-10			
			Min	Max	Min	Max	Min	Max	Min	Max		
t _{IN}	Input pad and buffer delay			0.2		0.2		0.3		0.5	ns	
t _{IO}	I/O input pad and buffer delay			0.2		0.2		0.3		0.5	ns	
t _{FIN}	Fast input delay			2.2		2.1		2.5		1.0	ns	
t _{SEXP}	Shared expander delay			3.1		3.8		4.6		5.0	ns	
t _{PEXP}	Parallel expander delay			0.9		1.1		1.4		0.8	ns	
t _{LAD}	Logic array delay			2.6		3.3		4.0		5.0	ns	
t _{LAC}	Logic control array delay			2.5		3.3		4.0		5.0	ns	
t _{IOE}	Internal output enable delay			0.7		0.8		1.0		2.0	ns	
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.2		0.3		0.4		1.5	ns	
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		0.7		0.8		0.9		2.0	ns	
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.2		5.3		5.4		5.5	ns	
t _{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		4.0		5.0	ns	
t _{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		4.5		5.5	ns	
t _{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		9.0	ns	
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		4.0		5.0	ns	
t _{SU}	Register setup time		0.8		1.0		1.3		2.0		ns	
t _H	Register hold time		1.7		2.0		2.5		3.0		ns	
t _{FSU}	Register setup time of fast input		1.9		1.8		1.7		3.0		ns	
t _{FH}	Register hold time of fast input		0.6		0.7		0.8		0.5		ns	
t _{RD}	Register delay			1.2		1.6		1.9		2.0	ns	
t _{COMB}	Combinatorial delay			0.9		1.1		1.4		2.0	ns	
t _{IC}	Array clock delay			2.7		3.4		4.2		5.0	ns	
t _{EN}	Register enable time			2.6		3.3		4.0		5.0	ns	
t _{GLOB}	Global control delay			1.6		1.4		1.7		1.0	ns	
t _{PRE}	Register preset time			2.0		2.4		3.0		3.0	ns	
t _{CLR}	Register clear time			2.0		2.4		3.0		3.0	ns	

Table 28. EPM7032S Internal Timing Parameters Note (1)											
Symbol	Parameter	Conditions	Speed Grade								Unit
			-5 -6		-7		-10				
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PIA}	PIA delay	(7)		1.1		1.1		1.4		1.0	ns
t _{LPA}	Low-power adder	(8)		12.0		10.0		10.0		11.0	ns

Notes to tables:

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 29 and 30 show the EPM7064S AC operating conditions.

Symbol	Parameter	Conditions				Speed	Grade)			Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t _{SU}	Global clock setup time		2.9		3.6		6.0		7.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		2.5		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.5		0.5		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		3.2		4.0		4.5		5.0	ns
t _{CH}	Global clock high time		2.0		2.5		3.0		4.0		ns
t _{CL}	Global clock low time		2.0		2.5		3.0		4.0		ns
t _{ASU}	Array clock setup time		0.7		0.9		3.0		2.0		ns
t _{AH}	Array clock hold time		1.8		2.1		2.0		3.0		ns

Symbol	Parameter	Conditions	Speed Grade								
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t _{SU}	Global clock setup time		3.4		6.0		7.0		11.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.5		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.0		4.5		5.0		8.0	ns
t _{CH}	Global clock high time		3.0		3.0		4.0		5.0		ns
t _{CL}	Global clock low time		3.0		3.0		4.0		5.0		ns
t _{ASU}	Array clock setup time		0.9		3.0		2.0		4.0		ns
t _{AH}	Array clock hold time		1.8		2.0		5.0		4.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		6.5		7.5		10.0		15.0	ns
t _{ACH}	Array clock high time		3.0		3.0		4.0		6.0		ns
t _{ACL}	Array clock low time		3.0		3.0		4.0		6.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(2)	3.0		3.0		4.0		6.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t _{CNT}	Minimum global clock period			6.8		8.0		10.0		13.0	ns
fcnt	Maximum internal global clock frequency	(4)	147.1		125.0		100.0		76.9		MHz
t _{acnt}	Minimum array clock period			6.8		8.0		10.0		13.0	ns
facnt	Maximum internal array clock frequency	(4)	147.1		125.0		100.0		76.9		MHz
f _{MAX}	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz

Tables 31 and 32 show the EPM7128S AC operating conditions.

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Table 3	4. EPM7160S Internal 1	<i>Timing Parameters</i>	s (Part)	2 of 2)	No	te (1)						
Symbol	Parameter	Conditions	Speed Grade									
			-6		-7		-10		-15			
			Min	Max	Min	Max	Min	Max	Min	Max		
t _{CLR}	Register clear time			2.4		3.0		3.0		4.0	ns	
t _{PIA}	PIA delay	(7)		1.6		2.0		1.0		2.0	ns	
t _{LPA}	Low-power adder	(8)		11.0		10.0		11.0		13.0	ns	

Notes to tables:

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more (1)information on switching waveforms.
- This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter (2)must be added to this minimum width if the clear or reset signal incorporates the t_{IAD} parameter into the signal path.

This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This (3) parameter applies for both global and array clocking.

These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB. (4)

- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use. (6)

For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, (7) these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.

(8)The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 35 and 36 show the EPM7192S AC operating conditions.

Table 35. EPM7192S External Timing Parameters (Part 1 of 2) Note (1)											
Symbol	Parameter	Conditions	Speed Grade								
			-7		-10		-15				
			Min	Max	Min	Max	Min	Max			
t _{PD1}	Input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns		
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns		
t _{SU}	Global clock setup time		4.1		7.0		11.0		ns		
t _H	Global clock hold time		0.0		0.0		0.0		ns		
t _{FSU}	Global clock setup time of fast input		3.0		3.0		3.0		ns		
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.0		ns		
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.7		5.0		8.0	ns		
t _{CH}	Global clock high time		3.0		4.0		5.0		ns		
t _{CL}	Global clock low time		3.0		4.0		5.0		ns		
t _{ASU}	Array clock setup time		1.0		2.0		4.0		ns		

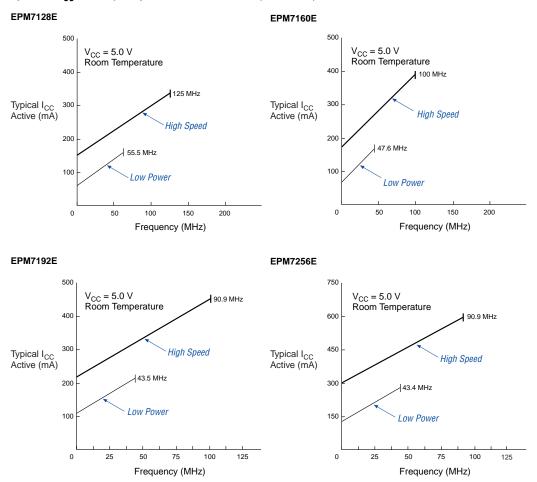
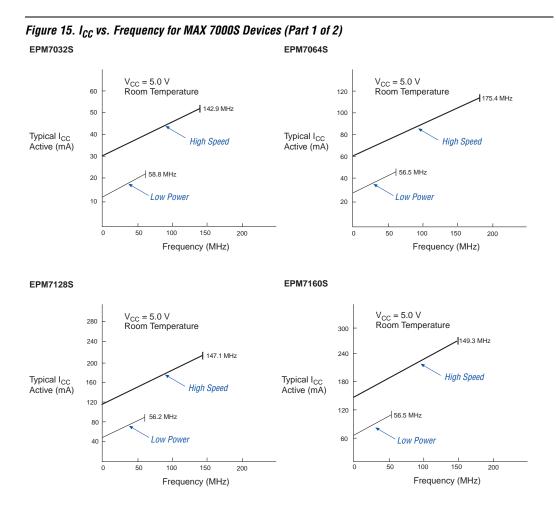


Figure 14. I_{CC} vs. Frequency for MAX 7000 Devices (Part 2 of 2)

Figure 15 shows typical supply current versus frequency for MAX 7000S devices.



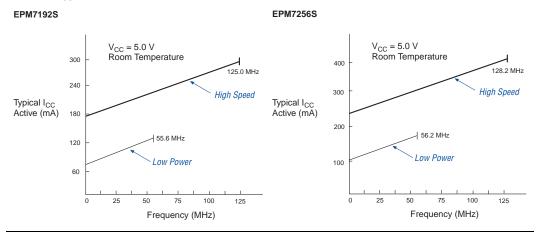


Figure 15. I_{CC} vs. Frequency for MAX 7000S Devices (Part 2 of 2)

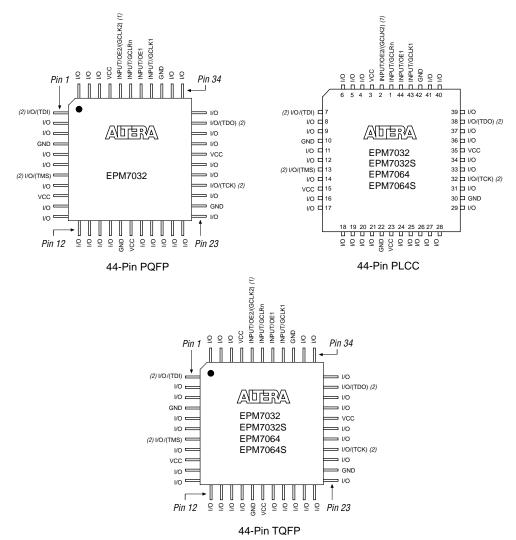
Device Pin-Outs

See the Altera web site (http://www.altera.com) or the *Altera Digital Library* for pin-out information.

Figures 16 through 22 show the package pin-out diagrams for MAX 7000 devices.

Figure 16. 44-Pin Package Pin-Out Diagram

Package outlines not drawn to scale.



Notes:

- (1) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (2) JTAG ports are available in MAX 7000S devices only.



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